multicomp

RoHS

Compliant



Description:

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC HH series MLCC is used at high frequencies generally have a small temperature coefficient of capacitance, typical within the ±30ppm/°C required for NP0 (C0G) classification and have excellent conductivity internal electrode. Thus, WTC HH series MLCC will be with the feature of low ESR and high Q characteristics.

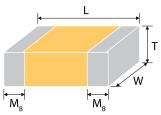
Features:

- High Q and low ESR performance at high frequency
- Quality improvement of telephone calls for low power loss and better performance

Applications:

- · Mobile telecommunication: Mobile phone, WLAN
- RF module: Power amplifier, VCO
- Tuners

External Dimensions:



Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol		Remark	MB (mm)
0402 (1005)	1±0.05	0.5±0.05	0.5±0.05	Ν	#	0.25 +0.05/-0.1
	1.6±0.1	0.8±0.1	0.8±0.07	S		
0603 (1608)	1.6 +0.15/-0.1	0.8 +0.15/-0.1	0.8 +0.15/-0.1	х		0.4±0.15

The outline of MLCC

Reflow soldering only is recommended.

General Electrical Data:

Dielectric	NP0
Size	0402, 0603
Capacitance*	0402: 0.5pF to 470pF** & 0603: 0.5pF to 3300pF
	Cap≤5pF: B (±0.1pF), C (±0.25pF)
Capacitance tolerance	5pF <cap<10pf: (±0.25pf),="" (±0.5pf)<="" c="" d="" td=""></cap<10pf:>
	Cap≥10pF: F (±1%), G (±2%), J (±5%)
Rated voltage (WVDC)	16V, 25V, 50V, 100V, 200V, 250V, 500V, 630V
Q*	Cap<30pF: Q≥400+20C; Cap≥30pF: Q≥1,000
Insulation resistance at Ur	≥10GΩ or R×C≥100Ω-F whichever is smaller
Operating temperature	-55°C to +125°C
Capacitance change	±30ppm/°C
Termination	Ni/Sn (lead-free termination)

* Measured at the conditions of 25°C ambient temper ature and 30~70% related humidity.

Apply 1±0.2Vrms, 1MHz±10% for Cap≤1000pF and 1±0.2Vrms, 1kHz±10% for Cap>1,000pF.

** 0402, Capacitance <0.5pF: On request.





Capacitance Range

	DIELECTRIC NP0				DIELECTRIC		NP0											
	SIZE		0402			06	603			SIZE		0402			0603			
F	Rated Voltage		25	50	16	25	50	100		Rated Voltage		16	25	50	16	25	50	100
	0.5pF (0R5)	N^	N^	N^	S^	S^	S^	S^			39pF (390)	Ν	Ν	Ν	S	S	S	S
	0.6pF (0R6)	N^	N^	N^	S^	S^	S^	S^		[47pF (470)	Ν	Ν	Ν	S	S	S	S
	0.7pF (0R7)	N^	N^	N^	S^	S^	S^	S^			56pF (560)	Ν	Ν	Ν	S	S	S	S
	0.8pF (0R8)	N^	N^	N^	S^	S^	S^	S^			68pF (680)	Ν	Ν	Ν	S	S	S	S
	0.9pF (0R9)	N^	N^	N^	S^	S^	S^	S^			82pF (820)	Ν	Ν	Ν	S	S	S	S
	1.0pF (1R0)	N^	N^	N^	S^	S^	S^	S^			100pF (101)	Ν	Ν	Ν	S	S	S	S
	1.2pF (1R2)	N^	N^	N^	S^	S^	S^	S^			120pF (121)	Ν	Ν	Ν	S	S	S	S
	1.5pF (1R5)	N^	N^	N^	S^	S^	S^	S^			150pF (151)	Ν	Ν	Ν	S	S	S	S
	1.8pF (1R8)	N^	N^	N^	S^	S^	S^	S^			180pF (181)	Ν	Ν	Ν	S	S	S	S
	2.2pF (2R2)	N^	N^	N^	S^	S^	S^	S^			220pF (221)	Ν	Ν	Ν	S	S	S	S
ce	2.7pF (2R7)	N^	N^	N^	S^	S^	S^	S^	ce		270pF (271)	Ν	Ν	Ν	S	S	S	S
Capacitance	3.3pF (3R3)	N^	N^	N^	S^	S^	S^	S^	Capacitance		330pF (331)	Ν	Ν	Ν	S	S	S	S
pac	3.9pF (3R9)	N^	N^	N^	S^	S^	S^	S^	pac		390pF (391)	Ν	Ν	Ν	S	S	S	S
S	4.7pF (4R7)	N^	N^	N^	S^	S^	S^	S^	Ga		470pF (471)	Ν	Ν	Ν	S	S	S	S
	5.6pF (5R6)	N^	N^	N^	S^	S^	S^	S^			560pF (561)				S	S	S	S
	6.8pF (6R8)	N^	N^	N^	S^	S^	S^	S^			680pF (681)				S	S	S	S
	8.2pF (8R2)	N^	N^	N^	S^	S^	S^	S^			820pF (821)				S	S	S	S
	10pF (100)	Ν	Ν	Ν	S	S	S	S			1,000pF (102)				S	S	S	S
	12pF (120)	Ν	Ν	Ν	S	S	S	S			1,200pF (122)				Х	Х	Х	
	15pF (150)	Ν	N	Ν	S	S	S	S		[1,500pF (152)				Х	Х	Х	
	18pF (180)	Ν	N	Ν	S	S	S	S		[1,800pF (182)				Х	Х	Х	
	22pF (220)	Ν	Ν	Ν	S	S	S	S		[2,200pF (222)				Х	Х	Х	
	27pF (270)	Ν	Ν	Ν	S	S	S	S		[2,700pF (272)				Х	Х	Х	
	33pF (330)	Ν	N	Ν	S	S	S	S			3,300pF (332)				Х	Х	Х	

1. The letter in cell is expressed the symbol of product thickness.

2. The letter in cell with "^" mark is expressed product with Ag/Ni/Sn terminations.

3. 0402, Capacitance <0.5pF: On request.

4. For more information about products with special capacitance or other data, please contact WTC local representative

Packaging Dimension And Quantity:

Size	Thickness (mm)/Syml		Paper Tape			
Size	Thickness (mm)/Syml	101	7" reel	13" reel		
0402	0.5±0.05	N	10,000	20,000		
0603	0.8±0.07	S	4 000	15,000		
0603	0.8+0.15/-0.1	Х	4,000	15,000		

Unit : pieces





Reliability Test Conditions and Requirements:

No	Item	Test Condition	Requirements	
1	Visual and Mechanical	-	No remarkable defect Dimensions to conform to individual specification sheet	
2	Capacitance	Cap≤1,000pF, 1±0.2Vrms, 1MHz±10% Cap>1,000pF, 1±0.2Vrms, 1kHz±10%	Shall not exceed the limits given in the detailed spec	
3	Q/ D.F. (Dissipation Factor)	At 25°C ambient temperature	NP0: Cap≥30pF, Q≥1,000; Cap<30pF, Q≥400+20C	
		To apply voltage: (≤100V) 250% of rated voltage Duration: 1 to 5 sec Charge and discharge current less than 50mA		
4	Dielectric Strength	To apply voltage: 200V~300V ≥2 times V DC 500V~999V ≥1.5 times V DC Cut-off, set at 10mA TEST= 15 sec. RAMP=0	No evidence of damage or flash over during test	
	Insulation	Rated voltage:<200V To apply rated voltage for max. 120 sec.	≥10ΩG	
5	Resistance	Rated voltage:200~630V To apply rated voltage (500V max.) for 60 sec.	≥10GΩ or R×C≥100Ω-F whichever is smaller	
6	Temperature Coefficient	With no electrical load. Operating temperature: -55°C to +125°C at 25°C	Capacitance change: within ±30ppm/°C	
7	Adhesive Strength of Termination	Pressurizing force: 5N (≤0603) and 10N (>0603) Test time: 10±1 sec.	No remarkable damage or removal of the terminations	
8	Vibration Resistance	Vibration frequency: 10~55 Hz/min. Total amplitude: 1.5mm Test time: 6hrs. (Two hrs each in three mutually perpendicular directions.)	No remarkable damage Cap change and Q/D.F.: To meet initial spec.	
9	Solderability	Solder temperature: 235±5°C Dipping time: 2±0.5 sec.	95% min. coverage of all metalized area	
10	Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temp. for 24±2 hrs.	No remarkable damage Cap change: within ±5.0% or ±0.5pF whichever is larger (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)	



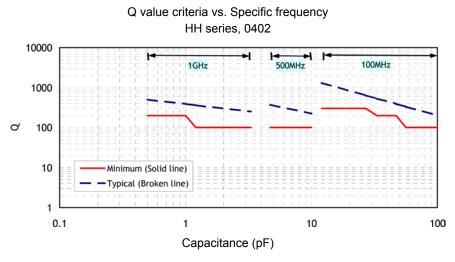


Reliability Test Conditions and Requirements:

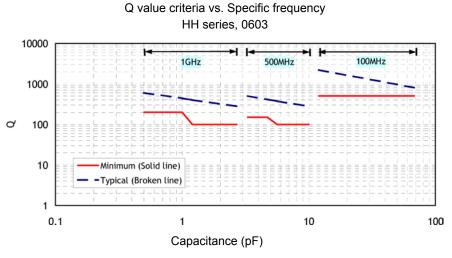
No	Item		Test Condition		Requirements		
11	Resistance to Soldering Heat	Dipping Preheat before in solder Measure	emperature: 260±5°C time: 10±1 sec ing: 120 to 150°C for 1 m mmerse the capacitor in a ement to be made after k mp. for 24±2 hrs. (Class I ass II)	a eutectic eeping at	No remarkable damage Cap change: within ±2.5% or ±0.25pF whichever is larger Q/D.F., I.R. and dielectric strength: To meet initial requirements 25% max. leaching on each edge		
			t the five cycles according atures and time	g to the			
		Step	Temp. (°C)	Time (Min.)			
		1	Min. operating temp. +0/-3	30 ±3	No remarkable damage Cap change: within ±2.5% or ±0.25pF whichever		
12	Temperature Cycle	2	Room temp.	2~3	is larger Q/D.F., I.R. and dielectric strength: To meet initial		
		3	Max. operating temp. +3/-0	30 ±3	requirements		
		4	Room temp.	2~3			
			ement to be made after k mp. for 24±2 hrs.	eeping at			
13	Humidity (Damp Heat) Steady State	Humidit Test tim Measur	np.: 40±2°C y: 90~95% RH e: 500+24/-0hrs. ement to be made after k temp. for 24±2 hrs.	eeping	No remarkable damage Cap change: within $\pm 5.0\%$ or ± 0.5 pF whichever is larger Q/D.F. value: NP0: Cap ≥ 30 pF, Q ≥ 350 ; 10pF \leq Cap < 30 pF, Q $\geq 275+2.5$ C Cap < 10 pF; Q $\geq 200+10$ C I.R.: ≥ 1 G Ω or RxC $\geq 50\Omega$ -F whichever is smaller		
14	Humidity (Damp Heat) Load	Humidit Test tim To apply 500V) Measure	np.: 40±2°C y: 90~95%RH e: 500+24/-0 hrs. / voltage: rated voltage (N ement to be made after k temp. for 24±2 hrs.		No remarkable damage. Cap change: within $\pm 7.5\%$ or $\pm 0.75pF$ whichever is larger. Q/D.F. value: NP0: Cap>30pF, Q>200; Cap<30pF, Q>100+10/3C I.R.: $\geq 500M\Omega$ or RxC>25 Ω -F whichever is smaller.		
15	High Temperature Load (Endurance)	(1) <500 (2) 500\ (3) ≥630 Test tim Measure	•		No remarkable damage. Cap change: within $\pm 3.0\%$ or $\pm 0.3pF$ whichever is larger. Q/D.F. value: NP0: Cap $\geq 30pF$, Q ≥ 350 $10pF \leq Cap < 30pF$, Q $\geq 275 + 2.5C$ Cap $< 10pF$, Q $\geq 200 + 10C$ I.R.: $\geq 1G\Omega$ or RxC $\geq 50\Omega$ -F whichever is smaller.		



Electrical Characteristics



Q factor specification vs. Specific frequency for 0402



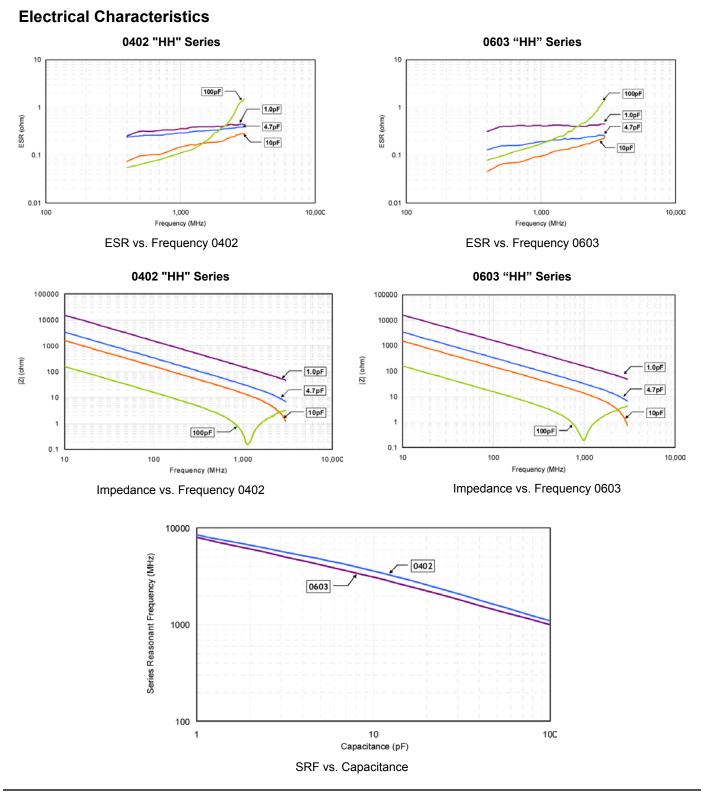
Q factor specification vs. Specific frequency for 0603

www.element14.com www.farnell.com www.newark.com



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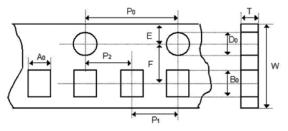




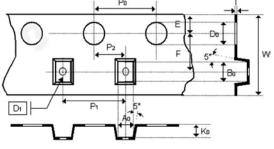
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Appendixes

Tape & Reel Dimensions

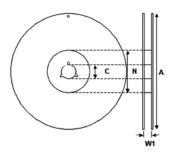


The dimension of paper tape



The dimension of plastic tape

Size	0402	0603
Thickness	N	S, X
Ao	0.62 ±0.05	1.02 ±0.05
Bo	1.12 ±0.05	1.8 ±0.05
Т	0.6 ±0.05	0.95 ±0.05
Ko	-	-
W	8 ±0.1	8 ±0.1
P ₀	4 ±0.1	4 ±0.1
10×P0	40 ±0.1	40 ±0.1
P1	2 ±0.05	4 ±0.1
P2	2 ±0.05	2 ±0.05
Do	1.55 ±0.05	1.55 ±0.05
D1	-	-
E	1.75 ±0.05	1.75 ±0.05
F	3.5 ±0.05	3.5 ±0.05



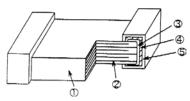
Size 0402 & 0603 **Reel size** 7" 13" С 13 +0.5/-0.2 13 +0.5/-0.2 W1 8.4 +1.5/-0 8.4 +1.5/-0 178 ±0.1 250 ±1 Α 60 +1/-0 Ν 100 ±1

The dimension of reel





Constructions:



The construction of MLCC

No.	Na	me	NP0*	NP0	
1	Ceramic	material	CaZrO3 / BaTiO3 based		
2	Inner el	ectrode	AgPd alloy	Ni	
3		Inner layer	Ag	Cu	
4	Termination	Middle layer	١	Vi	
5		Outer layer	S	'n	

* Partial NP0 items are with Ag/Ni/Sn(NME) terminations, please ref to product range for detail.

Storage and handling conditions

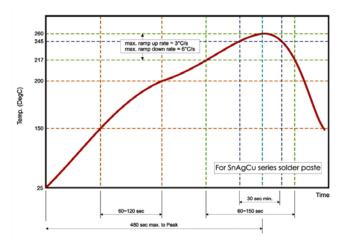
- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

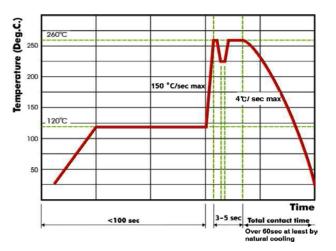
- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

Recommended soldering conditions:

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.



Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.



Recommended wave soldering profile for SMT process with SnAgCu series solder.



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Part Number Table

Description	Part Number
Capacitor, RF, 0.5PF, 50V, NP0, 0402	MC000269
Capacitor, RF, 0.5PF, 50V, NP0, 0402	MC000270
Capacitor, RF, 0.6PF, 50V, NP0, 0402	MC000271
Capacitor, RF, 0.8PF, 50V, NP0, 0402	MC000272
Capacitor, RF, 10PF, 50V, NP0, 0402	MC000273
Capacitor, RF, 100PF, 50V, NP0, 0402	MC000274
Capacitor, RF, 1PF, 50V, NP0, 0402	MC000275
Capacitor, RF, 1PF, 50V, NP0, 0402	MC000276
Capacitor, RF, 1.2PF, 50V, NP0, 0402	MC000277
Capacitor, RF, 1.5PF, 50V, NP0, 0402	MC000278
Capacitor, RF, 1.5PF, 50V, NP0, 0402	MC000279
Capacitor, RF, 1.8PF, 50V, NP0, 0402	MC000280
Capacitor, RF, 1.8PF, 50V, NP0, 0402	MC000281
Capacitor, RF, 2.2PF, 50V, NP0, 0402	MC000282
Capacitor, RF, 2.2PF, 50V, NP0, 0402	MC000283
Capacitor, RF, 2.7PF, 50V, NP0, 0402	MC000284
Capacitor, RF, 3PF, 50V, NP0, 0402	MC000285
Capacitor, RF, 3.9PF, 50V, NP0, 0402	MC000286
Capacitor, RF, 3.9PF, 50V, NP0, 0402	MC000287
Capacitor, RF, 4.7PF, 50V, NP0, 0402	MC000288
Capacitor, RF, 4.7PF, 50V, NP0, 0402	MC000289
Capacitor, RF, 5.1PF, 50V, NP0, 0402	MC000290
Capacitor, RF, 5.6PF, 50V, NP0, 0402	MC000291
Capacitor, RF, 6.8PF, 50V, NP0, 0402	MC000292
Capacitor, RF, 6.8PF, 50V, NP0, 0402	MC000293
Capacitor, RF, 6.8PF, 50V, NP0, 0402	MC000294
Capacitor, RF, 8.2PF, 50V, NP0, 0402	MC000295
Capacitor, RF, 0.75PF, 50V, NP0, 0402	MC000296
Capacitor, RF, 100PF, 50V, NP0, 0603	MC000297
Capacitor, RF, 1PF, 50V, NP0, 0603	MC000298
Capacitor, RF, 2.2PF, 50V, NP0, 0603	MC000299
Capacitor, RF, 2.7PF, 50V, NP0, 0603	MC000300
Capacitor, RF, 3.3PF, 50V, NP0, 0603	MC000301

